



**BRIGHTTEK**  
**BRIGHTTEK (EUROPE) LIMITED**

*Brighten up The World With LED!*



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

## PRODUCT DATASHEET



- ▶ PLCC2
- ▶ 3020 Series
- ▶ Warm White (3000K)

NOW02S25



Release Date: 23 December 2013 Version: A1.1



### 3020 Series



#### FEATURES:

- **Package:** PLCC White SMT Package
- **Forward Current:** 150mA
- **Forward Voltage (typ.):** 3.2V
- **Luminous Flux (typ.):** 55lm @150mA
- **Colour:** Warm White
- **CCT:** 3000K
- **Viewing angle:** 120°
- **Materials:**
  - Die: InGaN
  - Resin: Silicon (Yellow Diffused)
- **Operating Temperature:** -20~+80°C
- **Storage Temperature:** -30~+100°C
- **ESD:** 500V
- **Grouping parameters:**
  - Forward voltage
  - Luminous flux
  - CIE Chromaticity
- **Soldering methods:** IR Reflow soldering
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with 2000/reel, ø180mm (7")

#### APPLICATIONS:

- LCD Backlighting
- General Lighting
- Commercial Lighting
- Residential Lighting
- Architectural Lighting
- Flash Lighting

## CHARACTERISTICS:

### Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	$I_F$	150	mA
Peak Forward Current Duty 1/11@10KHz	$I_{FP}$	300	mA
Reverse Current @5V	$I_R$	10	$\mu$ A
Power Dissipation	PD	0.5	W
Electrostatic Discharge	ESD	500	V
Operating Temperature	$T_{OPR}$	-20~+80	°C
Storage Temperature	$T_{STG}$	-30~+100	°C
Colour Rendering Index	CRI	>80	---

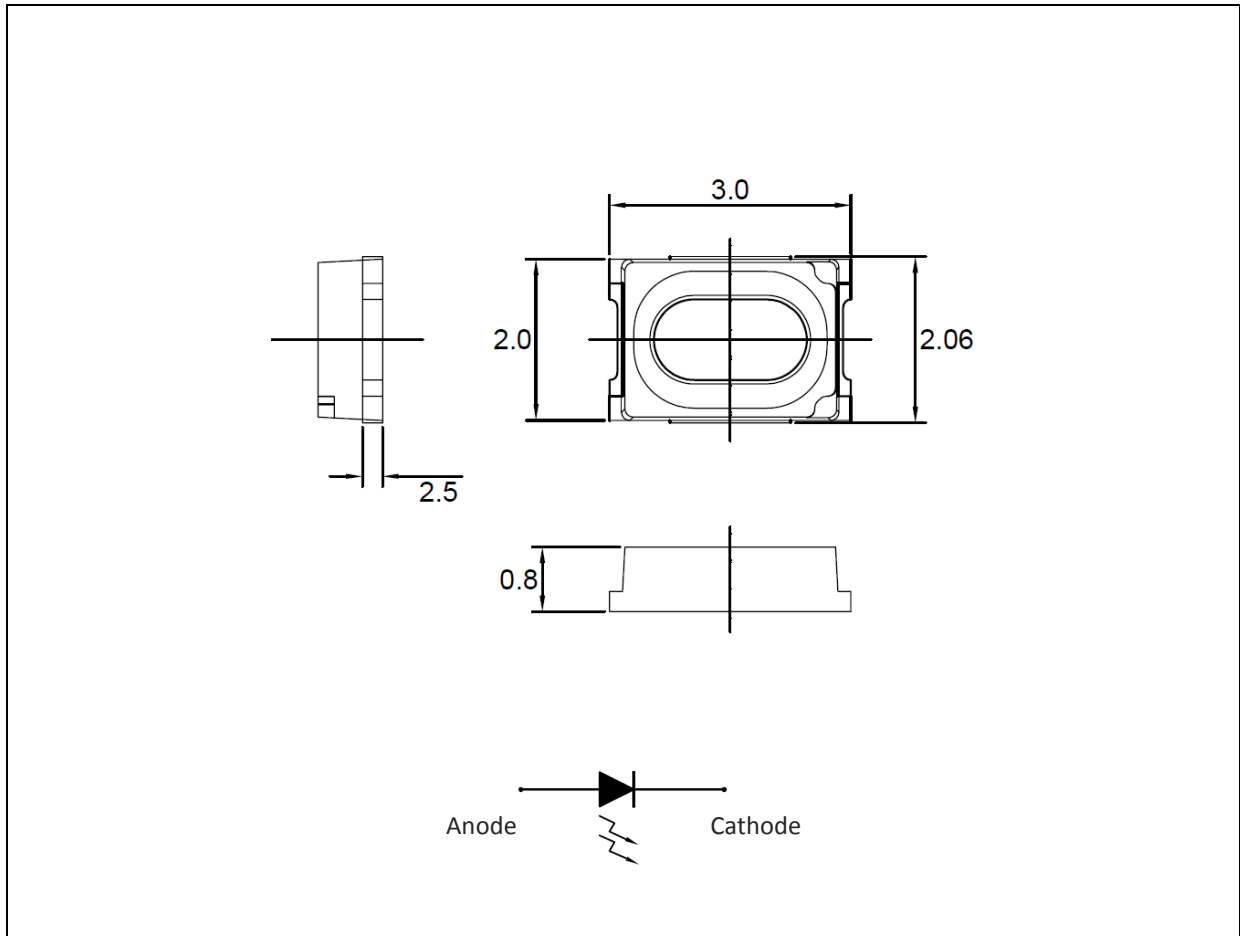
### Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	$V_F$	2.8	---	3.8	V	$I_F=150$ mA
Luminous Flux	$\Phi_V$	45	55	---	lm	$I_F=150$ mA
Chromaticity Coordinates	X	0.414	---	0.456	---	$I_F=150$ mA
	Y	0.381	---	0.421		
Colour Temperature	CCT	---	3000	---	K	
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	$I_F=150$ mA

1. Luminous intensity ( $I_v$ )  $\pm 15\%$ , Forward Voltage ( $V_F$ )  $\pm 0.1$ V, Viewing angle( $2\theta_{1/2}$ )  $\pm 5\%$ , CRI  $\pm 3$
2. IS standard testing

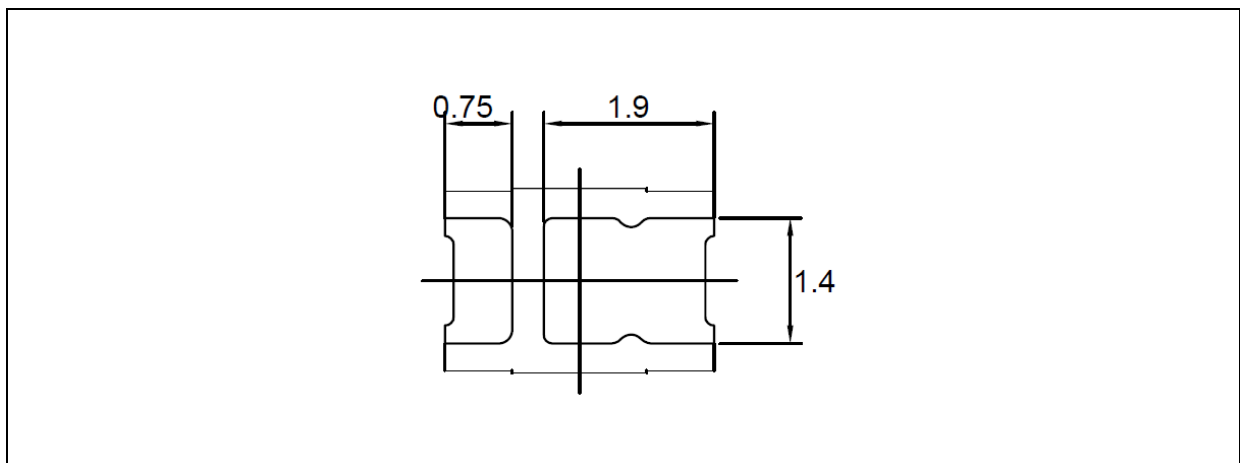
## OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1\text{mm}$ , unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1\text{mm}$  with angle tolerance  $\pm 0.5^\circ$ .

**BINNING GROUPS:**

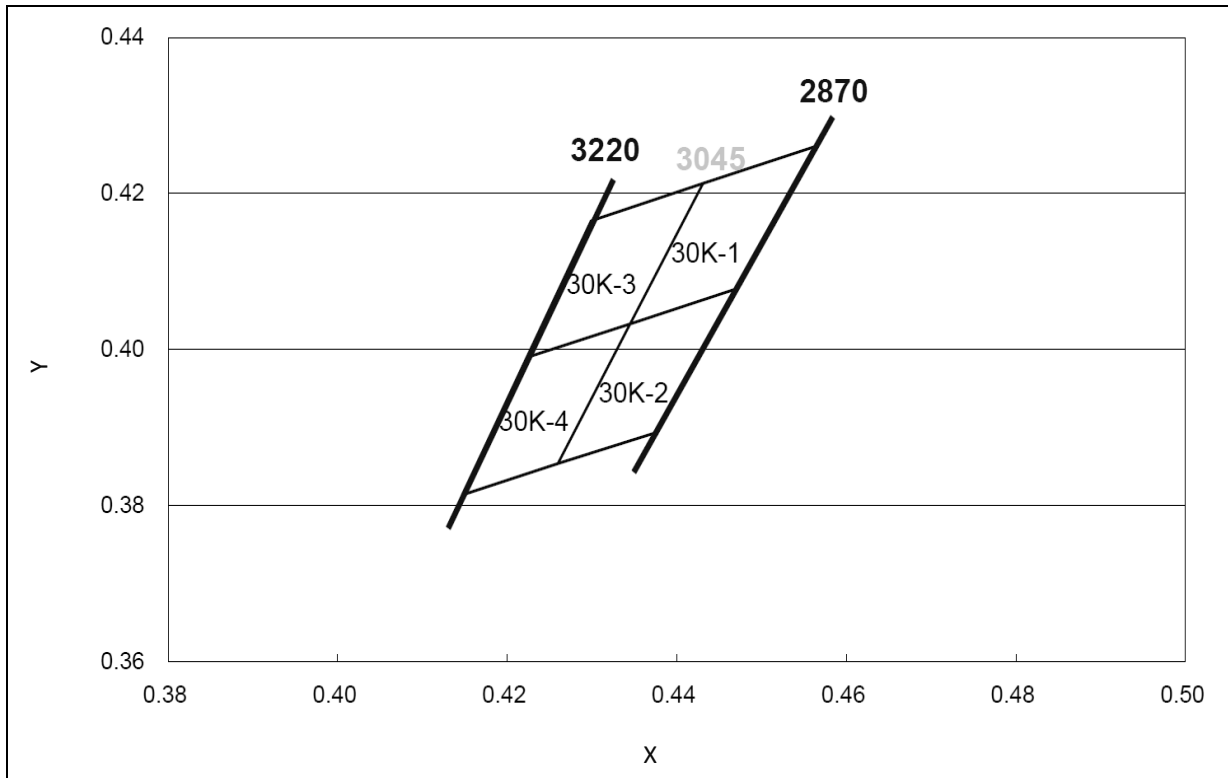

---

 Forward Voltage Classifications ( $I_F = 150\text{mA}$ ):

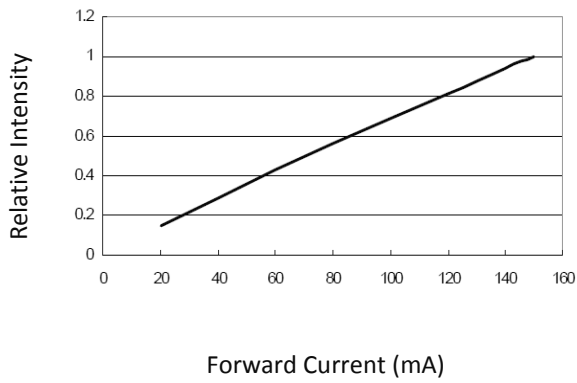
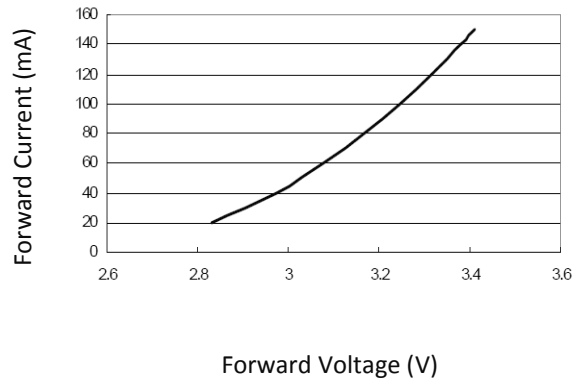
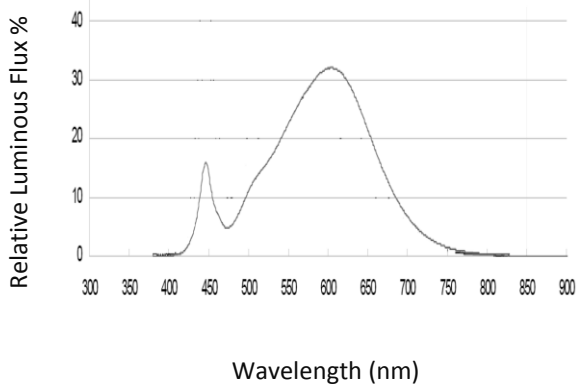
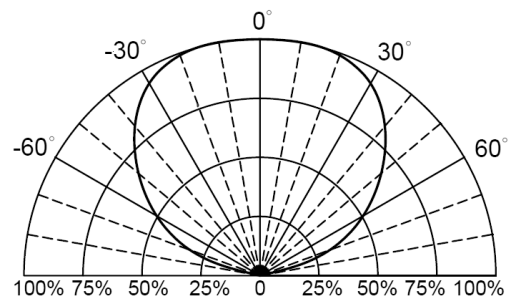
Code	Min.	Max.	Unit
1	2.8	2.9	V
2	2.9	3.0	
3	3.0	3.1	
4	3.1	3.2	
5	3.2	3.3	
6	3.3	3.4	
7	3.4	3.5	
8	3.5	3.6	
9	3.6	3.7	
10	3.7	3.8	

 Luminous Flux Classifications ( $I_F = 150\text{mA}$ ):

Code	Min.	Max.	Unit
F45V	45	50	lm
F50V	50	55	
F55V	55	60	
F60V	60	65	
F65V	65	70	
F70V	70	75	
F75V	75	80	

**CIE CHROMATICITY DIAGRAM:**

**Chromaticity Coordinates Classifications ( $I_F = 150\text{mA}$ ):**

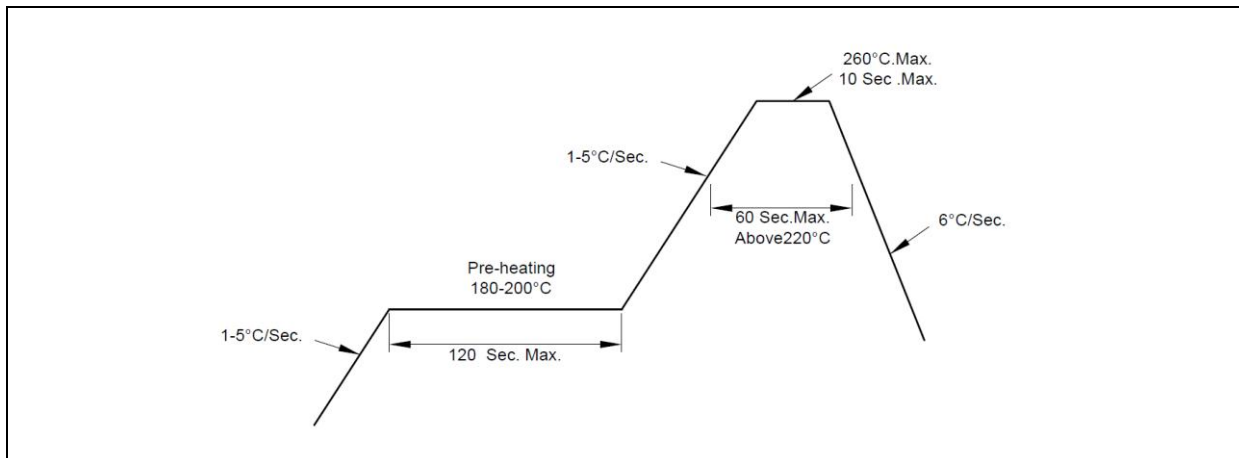
	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
30K-1	0.4562	0.4260	0.4431	0.4213	0.4345	0.4033	0.4468	0.4077
30K-2	0.4468	0.4077	0.4345	0.4033	0.4260	0.3854	0.4373	0.3893
30K-3	0.4431	0.4213	0.4299	0.4165	0.4223	0.3990	0.4345	0.4033
30K-4	0.4345	0.4033	0.4223	0.3990	0.4147	0.3814	0.4260	0.3854

**ELECTRO-OPTICAL CHARACTERISTICS:**
**Relative Intensity v.s. Forward Current**

**Forward Current v.s. Forward Voltage**

**Luminous Spectrum**

**Directive Radiation**


## RECOMMENDED SOLDERING PROFILE:

---

Lead-free Solder:

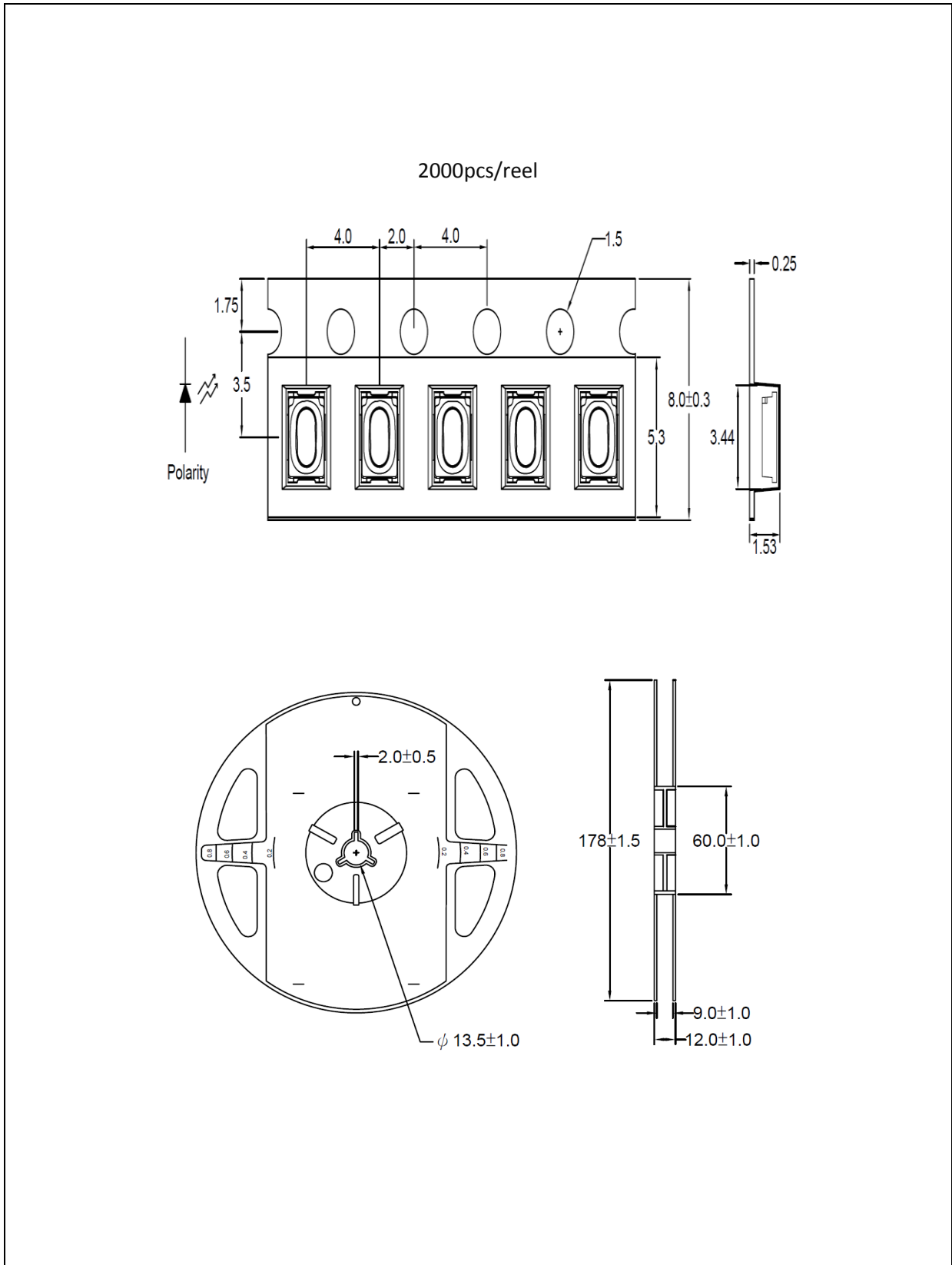


Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

**PACKING SPECIFICATION:**

Reel Dimension:





## PRECAUTIONS OF USE:

---

### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

### Baking:

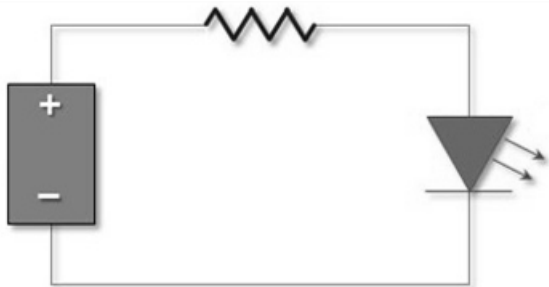
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs.

The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.